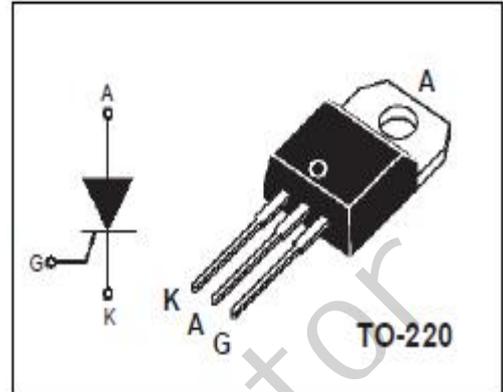


DESCRIPTION

- With TO-220 packaging
- Long-term stability
- Thyristor for line frequency
- Planar passivated chip
- Minimum Lot-to-Lot variations for robust device performance and reliable operation

APPLICATIONS

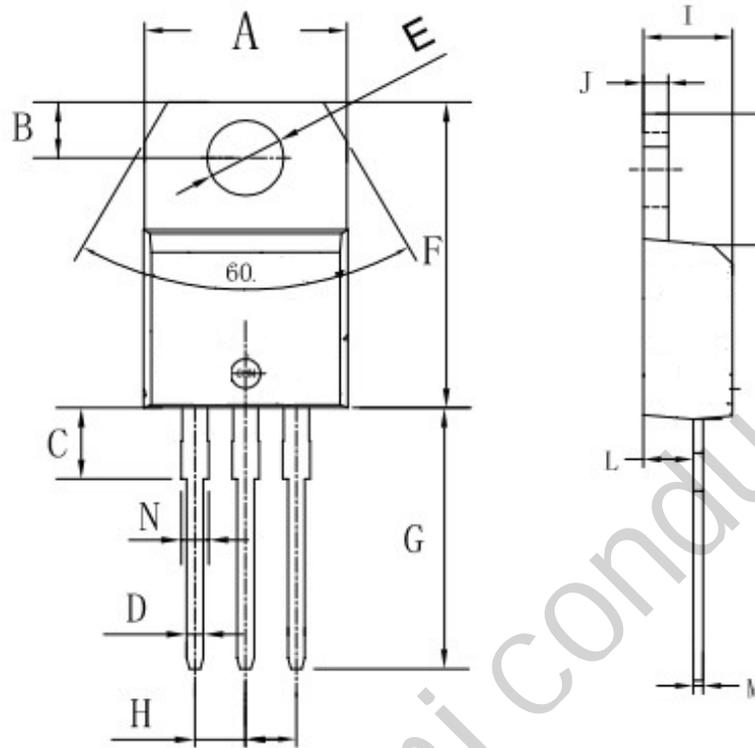
- Switching applications
- Line rectifying 50/60 Hz


ABSOLUTE MAXIMUM RATINGS (T_a=25°C)

SYMBOL	PARAMETER	MIN	UNIT
V _{DRM}	Repetitive peak off-state voltage	1200	V
V _{RRM}	Repetitive peak reverse voltage	1200	V
I _{T(AV)}	Average forward current	16	A
I _{T(RMS)}	RMS on-state current	25	A
I _{TSM}	Surge non-repetitive on-state current (1/2 cycle, sine wave; T _c =45°C)	260 250	A
P _{G(AV)}	Average gate power dissipation	0.5	W
T _j	Operating junction temperature	-40~125	°C
T _{stg}	Storage temperature	-40~150	°C

ELECTRICAL CHARACTERISTICS (T_c=25°C unless otherwise specified)

SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
I _{RRM}	Repetitive peak reverse current	V _{RM} =V _{RRM} V _{DM} =V _{DRM}		0.01 4	mA
I _{DRM}	Repetitive peak off-state current				
V _{TM}	On-state voltage	I _{TM} = 50A; t _p =380 μ s		1.6	V
I _{GT}	Gate-trigger current	V _D = 12V; R _L =33 Ω		40	mA
V _{GT}	Gate-trigger voltage	V _D = 12V; R _L =33 Ω		1.5	V
R _{th(j-c)}	Thermal resistance	Junction to case		1.3	°C/W

TO-220AB PACKAGE OUTLINE DIMENSIONS


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	9.8	10.4	0.385	0.409
B	2.65	3.1	0.104	0.122
C	2.8	4.2	0.110	0.165
D	0.7	0.92	0.027	0.036
E	3.75	3.95	0.147	0.155
F	14.8	16.1	0.582	0.633
G	13.05	13.6	0.513	0.535
H	2.4	2.7	0.094	0.106
I	4.38	4.61	0.172	0.181
J	1.15	1.36	0.045	0.053
K	5.85	6.82	0.230	0.268
L	2.35	2.75	0.092	0.108
M	0.35	0.65	0.013	0.025
N	1.18	1.42	0.046	0.055